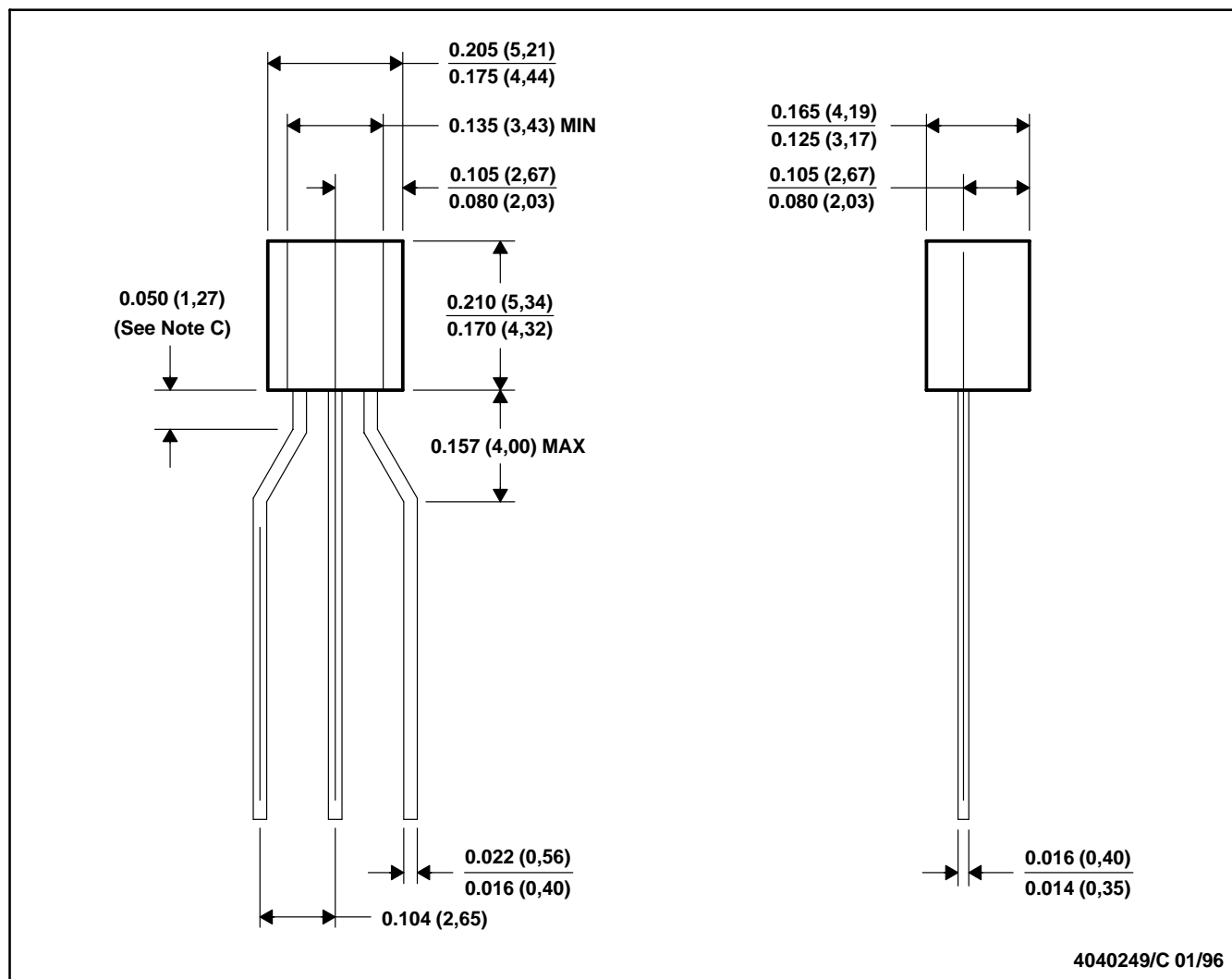


LPF (O-PBCY-W3)

PLASTIC CYLINDRICAL PACKAGE

FORMED LEADS



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Lead dimensions are not controlled within this area.

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